SDFS058B - D293, MARCH 1987 - REVISED MAY 2002

- Contains Four Flip-Flops With Double-Rail Outputs
- Buffered Clock and Direct Clear Inputs
- Applications Include:
 - Buffer/Storage Registers
 - Shift Registers
 - Pattern Generators

description

This positive-edge-triggered flip-flop utilizes TTL circuitry to implement D-type flip-flop logic with a direct clear ($\overline{\text{CLR}}$) input. Information at the data (D) inputs meeting setup-time requirements is transferred to outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When the clock (CLK) input is at either the high or low level, the D-input signal has no effect at the output.

, ,				KAGE						
	(TOP VIEW)									
CLR [1	U	16	V _{CC}						
1 <u>Q</u> [2		15] 4Q						
1Q [3		14	4Q						
1D [4		13] 4D						
2D [5		12] 3D						
2Q [6		11	3Q						
2Q [7		10] 3Q						
GND [8		9	CLK						
				I						

ORDERING INFORMATION

TA	PACKA	GE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74F175N	SN74F175N
000 1- 7000	SOIC - D	Tube	SN74F175D	F175
0°C to 70°C	3010 - D	Tape and reel	SN74F175DR	F1/3
	SOP - NS	Tape and reel	SN74F175NSR	74F175

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

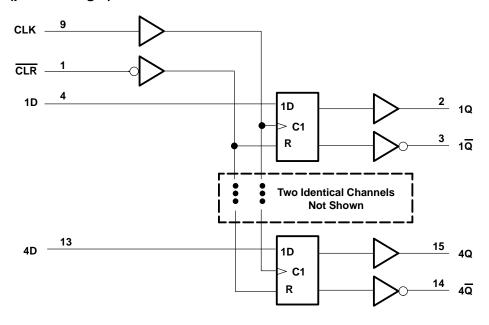
	INPUTS	OUTPUTS		
CLR	CLK	D	Q	Ø
L	Х	Χ	L	Н
Н	\uparrow	Н	Н	L
Н	\uparrow	L	L	Н
Н	L	Χ	Q_0	\overline{Q}_0



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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		
Input current range		
Voltage range applied to any output in the high		
Package thermal impedance, θ _{JA} (see Note 2)		
•	N package	67°C/W
	NS package	64°C/W
Storage temperature range, T _{stg}		. –65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input voltage ratings may be exceeded if the input current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
V _{IL}	Low-level input voltage			0.8	V
ΙΚ	Input clamp current			-18	mA
loн	High-level output current			-1	mA
lOL	Low-level output current			20	mA
TA	Operating free-air temperature	0		70	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
VIK	$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA			-1.2	V
VOH	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -1 \text{ mA}$	2.5	3.4		V
VOH	$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -1 \text{ mA}$	2.7			V
V _{OL}	$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 20 \text{ mA}$		0.3	0.5	V
lį	$V_{CC} = 5.5 \text{ V},$	V _I = 7 V			0.1	mA
lіН	$V_{CC} = 5.5 \text{ V},$	V _I = 2.7 V			20	μΑ
Ι _{ΙL}	$V_{CC} = 5.5 \text{ V},$	V _I = 0.5 V			- 0.6	mA
los [‡]	V _{CC} = 5.5 V,	V _O = 0	-60		-150	mA
Icc	$V_{CC} = 5.5 \text{ V},$	See Note 4		22.5	34	mA

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

			V _{CC} =	= 5 V, 25°C	MIN	MAX	UNIT
			MIN	MAX			
fclock	Clock frequency			100		100	MHz
		CLK high	4		4		
t _W	Pulse duration	CLK low	5		5	ns	ns
		CLR low	5		5		
_	Setup time, data before CLK↑	High or low	3		3		
t _{su}	Setup time, inactive state, data before CLK↑§	CLR high	5		5		ns
th	Hold time, data after CLK↑	High or low	1		1		ns

[§] Inactive-state setup time also is referred to as recovery time.

switching characteristics (see Figure 1)

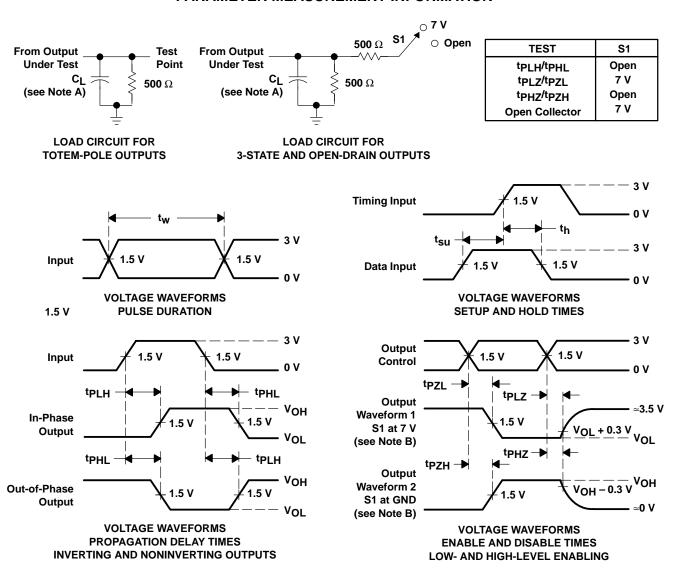
PARAMETER	FROM (INPUT)	TO (OUTPUT)	۷ ₀ ۲٫	CC = 5 V \(= 25°C	', ;	V _{CC} 4.5 V to	UNIT	
	(INFOT)	(001701)	MIN	TYP	MAX	MIN	MAX	
f _{max}			100	140		100		MHz
^t PLH	CLK	Q or $\overline{\mathbb{Q}}$	3.2	4.6	6.5	3.2	7.5	ns
^t PHL	OLK	Q or Q	3.2	6.1	8.5	3.2	9.5	115
^t PLH	CLR	Ισ	3.2	6.1	8.5	3.2	9	20
^t PHL	OLK	Q	3.7	8.6	11.5	3.7	13	ns



[‡] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 4: I_{CC} is measured with outputs open, with 4.5 V applied to all data inputs after a momentary ground, followed by 4.5 V applied to CLK.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns, duty cycle = 50%.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGE OPTION ADDENDUM



10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74F175D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	F175	Samples
SN74F175DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	F175	Samples
SN74F175N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74F175N	Samples
SN74F175NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74F175	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

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(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

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- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

10-Dec-2020

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74F175DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74F175NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

www.ti.com 30-Dec-2020



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74F175DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74F175NSR	SO	NS	16	2000	853.0	449.0	35.0

D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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